

03/24/2008

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application No.: 10/789,914  
Filing Date: February 27, 2004  
Applicant: Hosomi et al.  
Group Art Unit: 1714  
Examiner: Kriellion Sanders  
Title: Resin Composition, Prepeg, Laminate and  
Semiconductor Package  
Attorney Docket: 2497-000002/CP

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Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

**AMENDMENT UNDER 37 CFR 1.312**

Sir:

After the Notice of Allowance dated June 27, 2007 and before payment of the issue fee, please amend the application as follows and consider the remarks set forth below.

Please consider the following:

- ☒ Amendments to the Specification;
- ☐ Amendments to the Abstract;
- ☐ Amendments to the Claims;
- ☒ Amendments to the Drawings;
- ☒ **Remarks**